CC330x SimpleLink™ Wi-Fi 6 和低功耗 Bluetooth® 配套 IC

1 特性

关键特性

- Wi-Fi 6 (802.11ax)
- CC33x1 器件中的低功耗 Bluetooth® 5.4
- 能够运行 TCP/IP 堆栈的任何处理器或 MCU 主机的配套 IC
- 集成 2.4GHz PA，适用于输出功率高达 +20.5dBm 的完整无线解决方案。
- 工作温度：-40°C 至 +105°C
- 应用吞吐量高达 50Mbps

扩展特性

- Wi-Fi 6
  - 2.4GHz、20MHz、单空间流
  - 支持 IEEE 802.11 b/g/n/ax 的 MAC、基带和射频收发器
  - 目标唤醒时间 (TWT)、OFDMA、MU-MIMO（下行链路）、基本服务集着色和触发帧，可提高效率
  - 基于硬件的加密和解密，支持 WPA2 和 WPA3
  - 出色的互操作性
  - 支持 4 位 SDIO 或 SPI 主机接口
- 低功耗蓝牙 5.4
  - LE 编码 PHY（远距离）、LE 2M PHY（高速）和广播扩展
  - 主机控制器接口 (HCI) 传输，具有 UART 或共享 SDIO 的选项
- 增强的安全性
  - 安全主机接口
  - 固件身份验证
  - 防回滚保护
- 多角色支持（例如，并发 STA 和 AP），可连接不同射频通道（Wi-Fi 网络）上的 Wi-Fi 设备
- 可选天线分集或选择
- 3 线或 1 线 PTA，用于与额外 2.4GHz 无线电（例如 Thread 或 Zigbee）在外部共存
- 电源管理
  - V_{MAIN}、V_{IO}、V_{pp}：1.8V
  - V_{PA}：3.3V
- 时钟源
  - 40MHz XTAL 快速时钟
  - 内部慢速时钟或外部 32.768kHz 慢速时钟
- 小封装尺寸
  - 易于设计，采用 40 引脚 5mm x 5mm 四方扁平无引线 (QFN) 封装，间距为 0.4mm

2 应用

- 电网基础设施
  - 电量计
  - 串式逆变器
  - 微型逆变器
  - 能量存储电源转换系统 (PCS)
  - 电动汽车充电基础设施
- 楼宇和家居自动化
  - HVAC 控制器
  - HVAC 网关
  - 恒温器
  - 楼宇安全网关
  - 车库门系统
  - IP 网络摄像头/可视门铃
  - 无线安防摄像头
- 电器
  - 冰箱和冷冻柜
  - 烤箱
  - 洗衣机和烘干机
  - 住宅热水器和供暖系统
  - 空气净化器和加湿器
  - 咖啡机
  - 空调室内机
  - 扫地机器人
  - 割草机器人
- 医疗
  - 输液泵
  - 电子病床和床控制器
  - 多参数患者监护仪
  - 血压监护仪
  - CPAP 呼吸机
  - 远程保健系统
  - 超声波扫描仪
  - 超声波智能探头
  - 电动牙刷
- 零售自动化和支付
- 打印机

本资源的原文使用英文撰写。 为方便起见，TI 提供了译文；由于翻译过程中可能使用了自动化工具，TI 不保证译文的准确性。 为确认准确性，请务必访问 ti.com 参考最新的英文版本（控制文档）。

3 说明

SimpleLink™ Wi-Fi CC33xx 系列器件兼具经济性和可靠性，可支持工程师放心地连接更多应用。CC33xx 是单芯片 Wi-Fi 6 和低功耗蓝牙 5.4 器件。CC3300 和 CC3301 是此引脚对引脚兼容系列中的首批器件。

- CC3300：2.4GHz Wi-Fi 6 配套 IC。
- CC3301：2.4GHz Wi-Fi 6 和低功耗蓝牙 5.4 配套 IC。

CC330x 提供 Wi-Fi 6 和 BLE，同时与 Wi-Fi 4 (802.11 b/g/n) 和 Wi-Fi 5 (802.11ac) 保持兼容。这些 CC330x 器件是德州仪器 (TI) 的第 10 代连接组合芯片。因此，CC330x 基于成熟的技术设计而成。这些器件非常适合用在通过 Linux 或 RTOS 主机运行 TCP/IP 的成本敏感型嵌入式应用中，CC330x 为物联网 (IoT) 的嵌入式设备应用带来了 Wi-Fi 6 的效率，并具有较小的 PCB 尺寸和高度优化的物料清单。

器件信息

器件型号	Wi-Fi 2.4GHz SISO	蓝牙低耗能
CC3300ENJARSBR	✓	
CC3301ENJARSBR	✓	✓

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4 系统图

图 4-1 显示了 CC3301 的基本系统图。

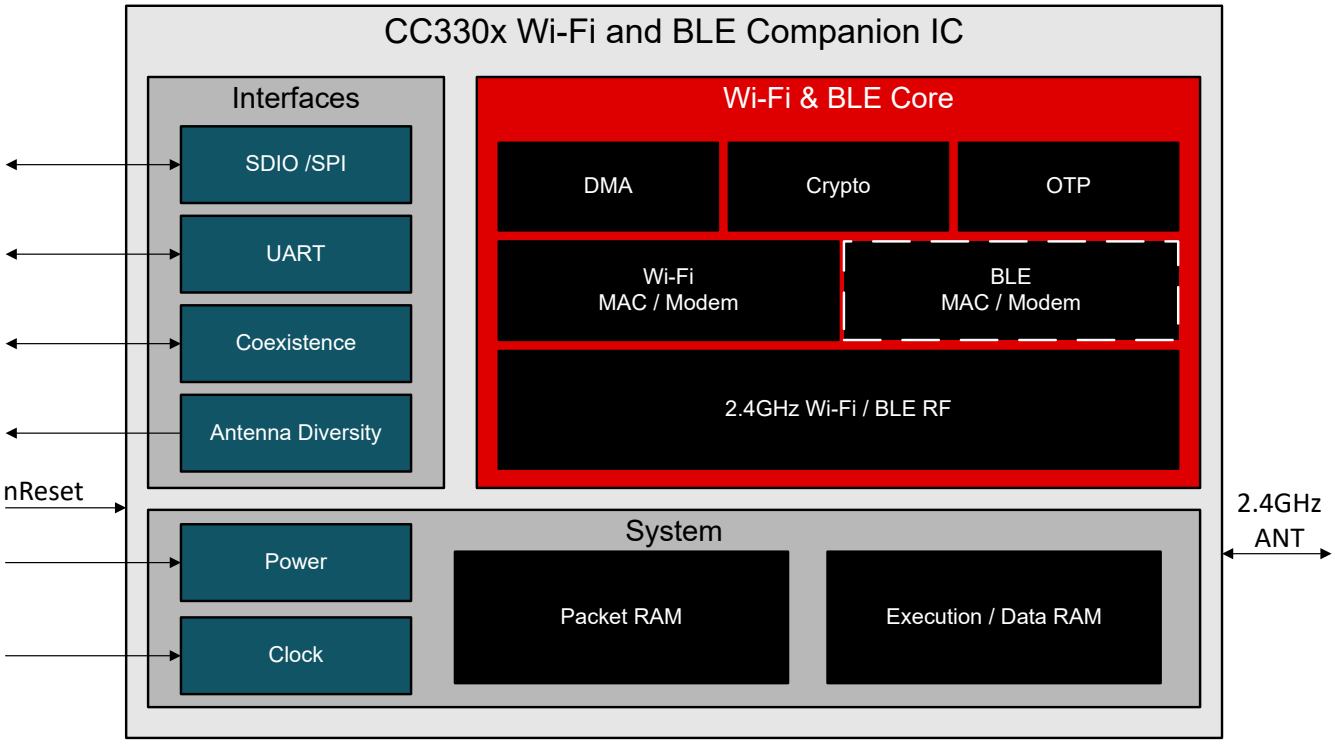

图 4-1. CC3301 系统简图

Table of Contents

1 特性 1
2 应用 1
3 说明 2
4 系统图 3
5 Terminal Configuration and Functions 5
5.1 Pin Diagram 5
5.2 Pin Attributes 6
6 Specifications 8
6.1 Absolute Maximum Ratings 8
6.2 ESD Ratings 8
6.3 Recommended Operating Conditions 8
6.4 Electrical Characteristics 9
6.5 Thermal Resistance Characteristics 9
6.6 WLAN Performance: 2.4-GHz Receiver Characteristics 9
6.7 WLAN Performance: 2.4-GHz Transmitter Power 10
6.8 BLE Performance: Receiver Characteristics 10
6.9 BLE Performance - Transmitter Characteristics 11
6.10 Current Consumption - WLAN Static Modes 12
6.11 Current Consumption - WLAN Use Cases 12
6.12 Current Consumption - BLE Static Modes 13
6.13 Current Consumption - Device States 13
6.14 Timing and Switching Characteristics 13
6.15 Interface Timing Characteristics 15
7 Applications, Implementation, and Layout 18
8 Device and Documentation Support 19
8.1 第三方产品免责声明 19
8.2 器件命名规则样板文件 19
8.3 Tools and Software 19
8.4 Documentation Support 20
8.5 支持资源 20
8.6 Trademarks 20
8.7 静电放电警告 21
8.8 术语表 21
9 Revision History 21
10 Mechanical, Packaging, and Orderable Information 22

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5 Terminal Configuration and Functions

5.1 Pin Diagram

图 5-1 shows pin assignments for the 40-pin WQFN package.

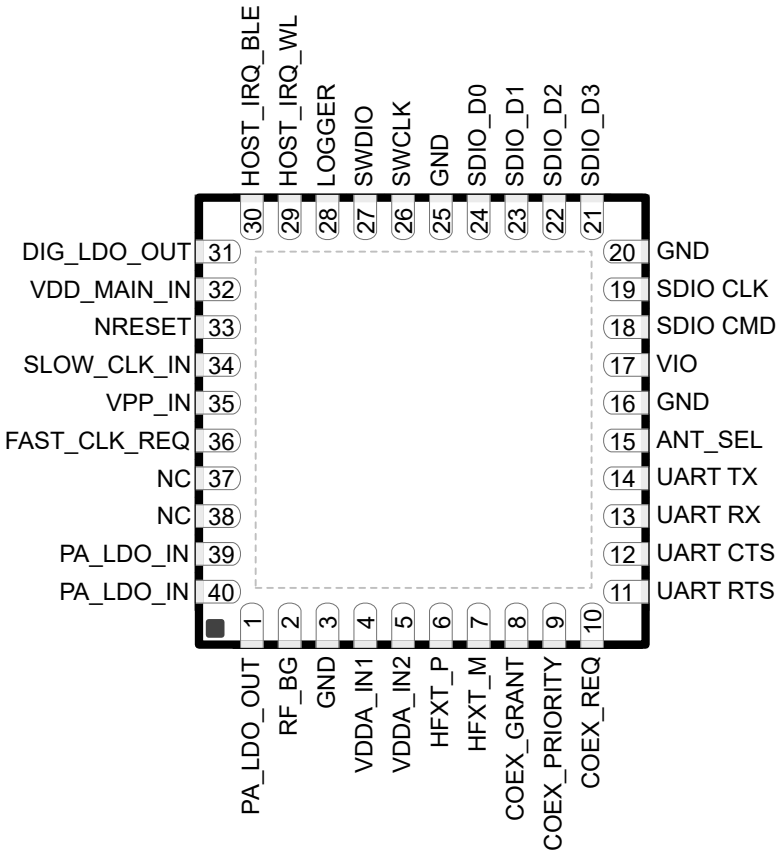

图 5-1. CC3301 Pin Diagram

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5.2 Pin Attributes

表 5-1. Pin Attributes

PIN	SIGNAL NAME	TYPE	DIR (I/O)	VOLTAGE LEVEL	SHUTDOWN STATE	STATE AFTER POWER-UP	DESCRIPTION
1	PA_LDO_OUT	Analog					RF power amplifier LDO output
2	RF_BG	RF	I/O				Bluetooth Low Energy and WLAN 2.4-GHz RF port
3	GND	GND					GND
4	VDDA_IN1	POW					1.8 V supply for analog domain
5	VDDA_IN2	POW					1.8 V supply for analog domain
6	HFXT_P	Analog		Sine			XTAL_P
7	HFXT_M	Analog					XTAL_N
8	COEX_GRANT[2]	Digital	O	V_{IO}	PD	PD	External coexistence interface - grant
9	COEX_PRIORITY[2]	Digital	I	V_{IO}	PU	PU	External coexistence interface - priority
10	COEX_REQ[2]	Digital	I	V_{IO}	PU	PU	External coexistence interface - request
11	UART RTS	Digital	O	V_{IO}	PU	PU	Device RTS signal - flow control for BLE HCI
12	UART CTS	Digital	I	V_{IO}	PU	PU	Device CTS signal - flow control for BLE HCI
13	UART RX	Digital	I	V_{IO}	PU	PU	UART RX for BLE HCI
14	UART TX	Digital	O	V_{IO}	PU	PU	UART TX for BLE HCI
15	ANT_SEL[2]	Digital	O	V_{IO}	PD	PD	Antenna select control line
16	GND	GND					GND
17	VIO	POW					1.8 V IO supply
18	SDIO CMD	Digital	I/O	V_{IO}	HiZ	HiZ	SDIO command or SPI PICO
19	SDIO CLK	Digital	I	V_{IO}	HiZ	HiZ	SDIO clock or SPI clock
20	GND	GND					GND
21	SDIO D3	Digital	I/O	V_{IO}	HiZ	PU	SDIO data D3 or SPI CS
22	SDIO D2	Digital	I/O	V_{IO}	HiZ	HiZ	SDIO data D2
23	SDIO D1	Digital	I/O	V_{IO}	HiZ	HiZ	SDIO data D1
24	SDIO D0	Digital	I/O	V_{IO}	HiZ	HiZ	SDIO data D0 or SPI POCI
25	GND	GND					GND
26	SWCLK	Digital	I	V_{IO}	PD	PD	Serial wire debug clock
27	SWDIO	Digital	I/O	V_{IO}	PU	PU	Serial wire debug I/O
28	LOGGER[3]	Digital	O	V_{IO}	PU	PU	Tracer (UART TX debug logger)
29	HOST_IRQ_WL[3]	Digital	O	V_{IO}	PD	0	Interrupt request to host for WLAN

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表 5-1. Pin Attributes（续）

PIN	SIGNAL NAME	TYPE	DIR (I/O)	VOLTAGE LEVEL	SHUTDOWN STATE	STATE AFTER POWER-UP	DESCRIPTION
30	HOST_IRQ_BLE[3]	Digital	O	V_{IO}	PD	PD	Interrupt request to host for BLE (in shared SDIO mode)
31	DIG_LDO_OUT	Analog	O				Digital LDO output to decoupling capacitor
32	VDD_MAIN_IN	POW					1.8 V supply input for SRAM and digital
33	nRESET	Digital	I	V_{IO}	PD	PD	Reset line for enabling or disabling device (active low)
34	SLOW_CLK_IN	Digital	I	V_{IO}	PD	PD	32.768-kHz RTC clock input
35	VPP_IN	POW					1.8 V OTP programming input supply
36	FAST_CLK_REQ	Digital	O	V_{IO}	PD	PD	Fast clock request from the device
37	NC	NC					Connect to GND
38	NC	NC					Connect to GND
39	PA_LDO_IN	POW					3.3 V supply for PA
40	PA_LDO_IN	POW					3.3 V supply for PA

1. All digital I/O's (with the exception of SDIO signals) are Hi-Z when the device is in shutdown mode with internal PU/PD according to the "shutdown state" column.
2. See software release notes for support level.
3. LOGGER and HOST_IRQ_WL pins are sensed by the device during boot, see CC33xx Hardware Integration.

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6 Specifications

All specifications are given at the CC3301 pins. Typical values are measured with nominal device at 25°C.

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)(1)

PARAMETER		PINS	MIN	MAX	UNIT
V_{PA}	V_{DD} PA Voltage	39,40	–0.5	4.2	V
V_{MAIN}	Main supply voltage for analog and digital - VDD_MAIN_IN, VDDA_IN1, VDDA_IN2	32, 4, 5	–0.5	2.1	V
V_{IO}	VDD IO Voltage	17	–0.5	2.1	V
	Input Voltage to all digital pins		–0.5	V_{IO} + 0.5	V
	HFXT_P Input Voltage	6	–0.5	2.1	V
V_{PP}	VPP OTP Voltage	35	–0.5	2.1	V
T_A	Operating Ambient Temperature		–40	105	°C
T_{stg}	Storage temperature		–55	155	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

				VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per AEC Q100-002(1)	RF pins	±1000	V
			Other pins	±2000	
		Charged device model (CDM), per AEC Q100-011	RF pins	±250	
			Other pins	±500	

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

PARAMETER		PINS	MIN	TYP	MAX	UNIT
V_{MAIN}	Main supply voltage digital and analog - VDD_MAIN_IN, VDDA_IN1, VDDA_IN2	32,4,5	1.62	1.8	1.98	V
V_{PA}	DC supply rail for PA	39,40	3	3.3	3.6	
V_{IO}	DC supply rail for input/output	17	1.62	1.8	1.98	
V_{PP}	DC supply rail for OTP memory	35	1.62	1.8	1.98	
T_A	Operating ambient temperature		–40		85/105(1)	°C
	Maximum power dissipation				2	W

(1) The CC3300 and CC3301 devices may operate at temperatures of up to 105°C. This allows the device to be used reliably in applications that may be exposed to higher ambient temperature over certain periods of the product’s life. At temperatures higher than 85°C, the WLAN/BLE performance may degrade.

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6.4 Electrical Characteristics

PARAMETER	DESCRIPTION	TEST CONDITION	MIN	TYP	MAX	UNIT
V_{IH}	High Level Input Voltage		0.65 x V_{IO}		V_{IO}	V
V_{IL}	Low Level Input Voltage		0		0.35 x V_{IO}	
V_{OH}	High Level Output Voltage	at 4mA	V_{IO} – 0.45		V_{IO}	
V_{OL}	Low Level Output Voltage	at 4mA	0		0.45	

6.5 Thermal Resistance Characteristics

THERMAL METRIC(1)	DESCRIPTION		UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance (According to JEDEC EIA/JESD 51 document)	30.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	16.7	
$R_{\theta JB}$	Junction-to-board thermal resistance	10	
Ψ_{JT}	Junction-to-top characterization parameter	0.1	
Ψ_{JB}	Junction-to-board characterization parameter	10	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	1.7	

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.6 WLAN Performance: 2.4-GHz Receiver Characteristics

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Operational Frequency Range		2412		2472	MHZ
Sensitivity: 8% PER for 11b rates, 10% PER for 11g/n/ax rates	1 Mbps DSSS		-98		dBm
	2 Mbps DSSS		-95.3		
	11 Mbps CCK		-90		
	6 Mbps OFDM		-93.2		
	54 Mbps OFDM		-75.5		
	HT MCS0 MM 4K		-93		
	HT MCS7 MM 4K		-72.9		
	HE MCS0 4K		-92.7		
	HE MCS7 4K		-72.5		
Maximum input level: 8% PER for 11b rates, 10% PER for 11g/n/ax rates	1 DSSS		0		dBm
	OFDM6, HT MCS0, HE MCS0		0		
	OFDM54, HT MCS7, HE MCS7		-9		
Adjacent Channel Rejection	1 Mbps DSSS		45		dB
	11 Mbps CCK		39		
	6 Mbps OFDM		20		
	54 Mbps OFDM		3		
	HT MCS0		20		
	HT MCS7		3		
	HE MCS0		16		
	HE MCS7		-1		
RSSI Accuracy	-90 dBm to -30dBm	-3		3	dB

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6.7 WLAN Performance: 2.4-GHz Transmitter Power

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Operational Frequency Range		2412		2472	MHz
Maximum output power at V_{PA} > 3.0 V	1 Mbps DSSS		20.5		dBm
	6 Mbps OFDM		20.2		
	54 Mbps OFDM		17.4		
	HT MCS0 MM		20.2		
	HT MCS7 MM		17.4		
	HE MCS0		20.2		
	HE MCS7		17.3		

6.8 BLE Performance: Receiver Characteristics

PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
BLE 125Kbps (LE Coded) Receiver Characteristics					
Receiver sensitivity	PER <30.2%		-102.2		dBm
Receiver saturation	PER <30.2%		0		dBm
Co-channel rejection(1)	Wanted signal at -79 dBm, modulated interferer in channel		10		dB
Selectivity, ±1 MHz(1)	Wanted signal at -79 dBm, modulated interferer at ±1 MHz.		0 / 0		dB
Selectivity, ±2 MHz(1)	Wanted signal at -79 dBm, modulated interferer at ±2 MHz.		-37 / -30		dB
Selectivity, ±3 MHz(1)	Wanted signal at -79 dBm, modulated interferer at ±3 MHz.		-39 / -36		dB
Selectivity, ±4 MHz(1)	Wanted signal at -79 dBm, modulated interferer at ±4 MHz.		-45 / -41		dB
RSSI Accuracy	Dynamic range of -90 to -20dBm	-4		4	dB
BLE 500Kbps (LE Coded) Receiver Characteristics					
Receiver sensitivity	PER <30.2%		-99.8		dBm
Receiver saturation	PER <30.2%		0		dBm
Co-channel rejection(1)	Wanted signal at -72 dBm, modulated interferer in channel.		10		dB
Selectivity, ±1 MHz(1)	Wanted signal at -72 dBm, modulated interferer at ±1 MHz.		0 / 0		dB
Selectivity, ±2 MHz(1)	Wanted signal at -72 dBm, modulated interferer at ±2 MHz.		-35 / -25		dB
Selectivity, ±3 MHz(1)	Wanted signal at -72 dBm, modulated interferer at ±3 MHz.		-40 / -37		dB
Selectivity, ±4 MHz(1)	Wanted signal at -72 dBm, modulated interferer at ±4 MHz.		-45 / -40		dB
RSSI Accuracy	Dynamic range of -90 to -20dBm	-4		4	dB
BLE 1Mbps (LE 1M) Receiver Characteristics					
Receiver sensitivity(2)	PER <30.2%, 37-byte packets		– 99.4		dBm
Receiver sensitivity(2)	PER <30.2%, 255 byte-packets		– 98.1		dBm
Receiver saturation	PER <30.2%		0		dBm
Co-channel rejection(1)	Wanted signal at -67 dBm, modulated interferer in channel		10		dB

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PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
Selectivity, ±1 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±1 MHz		0 / 0		dB
Selectivity, ±2 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±2 MHz.		-35 / -28		dB
Selectivity, ±3 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±3 MHz		-38 / -32		dB
Selectivity, ±4 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±4 MHz		-45 / -40		dB
Out-of-band blocking	30 MHz to 2000 MHz, Wanted signal at -67 dBm		– 23		dBm
Out-of-band blocking	2003 MHz to 2399 MHz, Wanted signal at -67 dBm		– 30		dBm
Out-of-band blocking	2484 MHz to 2997 MHz, Wanted signal at -67 dBm		– 30		dBm
Out-of-band blocking	3000 MHz to 6 GHz, Wanted signal at -67 dBm		– 21		dBm
Intermodulation	Wanted signal at 2402 MHz, -64 dBm. Two interferers at 2405 and 2408 MHz respectively, at the given power level		– 40		dBm
RSSI accuracy	Dynamic range of -90 to -20dBm	-4		4	dB
BLE 2Mbps (LE 2M) Receiver Characteristics					
Receiver sensitivity(3)	PER <30.2%		-95.2		dBm
Receiver saturation	PER <30.2%		0		dBm
Co-channel rejection(1)	Wanted signal at -67 dBm, modulated interferer in channel		10		dB
Selectivity, ±2 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±2 MHz.		0 / 0		dB
Selectivity, ±4 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±4 MHz		-35 / -28		dB
Selectivity, ±6 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±6 MHz		-35 / -28		dB
Alternate channel rejection, ±8 MHz(1)	Wanted signal at -67 dBm, modulated interferer at ±8 MHz		-37 / -32		dB
Out-of-band blocking	30 MHz to 2000 MHz, Wanted signal at -67 dBm		– 23		dBm
Out-of-band blocking	2003 MHz to 2399 MHz, Wanted signal at -67 dBm		– 30		dBm
Out-of-band blocking	2484 MHz to 2997 MHz, Wanted signal at -67 dBm		– 30		dBm
Out-of-band blocking	3000 MHz to 6 GHz, Wanted signal at -67 dBm		– 21		dBm
Intermodulation	Wanted signal at 2402 MHz, -64 dBm. Two interferers at 2405 and 2408 MHz respectively, at the given power level		– 44		dBm
RSSI Accuracy	Dynamic range of -90 to -20dBm	-4		4	dB

(1) Numbers given as C/I dB
(2) BLE 1M PHY sensitivity on channels 17 and 39 may degrade by up to 2.5 dB
(3) BLE 2M PHY sensitivity on channel 17 may degrade by up to 1.5 dB

6.9 BLE Performance - Transmitter Characteristics

The CC330X devices support BLE TX setting 0,5,10, or 20 dBm

PARAMETER	DESCRIPTION	MIN	TYP	MAX	UNIT
Output Power, highest setting			20		dBm

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6.10 Current Consumption - WLAN Static Modes

All results are based on measurements taken using the RadioTool evaluation application (typ values are taken with nominal devices at room temp).

PARAMETER	TEST CONDITION		SUPPLY	TYP	MAX	UNIT
Continuous TX(1)	1 DSSS	TX power = 20.5 dBm	V_{Main}	92		mA
			V_{PA}	250	290	
	6 OFDM	TX power = 20.2 dBm	V_{Main}	105	170	
			V_{PA}	250	290	
	54 OFDM	TX power = 17.4 dBm	V_{Main}	110		
			V_{PA}	180		
	HT MCS0	TX power = 20.2 dBm	V_{Main}	105		
			V_{PA}	245		
	HT MCS7	TX power = 17.4 dBm	V_{Main}	110		
			V_{PA}	180		
	HE MCS0	TX power = 20.2 dBm	V_{Main}	105		
			V_{PA}	240		
	HE MCS7	TX power = 17.3 dBm	V_{Main}	110		
			V_{PA}	180		
Continuous RX			V_{Main}	62		
			V_{PA}	0		

(1) Peak current V_{PA} can hit 340mA during device calibration.
Peak current V_{MAIN} of 185mA including periperhals and internal cortex

6.11 Current Consumption - WLAN Use Cases

Nominal device at room temp

MODE	DESCRIPTION	MIN	TYP	MAX	UNIT
DTIM=1	System with 3.3V to Ext. DC/DC at 85% efficiency WLAN beacon reception every DTIM=1 (~102ms)		637		µA
	System with 1.8V WLAN beacon reception every DTIM=1 (~102ms)		980		
DTIM=3	System with 3.3V to Ext. DC/DC at 85% efficiency WLAN beacon reception every DTIM=1 (~102ms)		371		
	System with 1.8V WLAN beacon reception every DTIM=1 (~102ms)		570		
DTM=5	System with 3.3V to Ext. DC/DC at 85% efficiency WLAN beacon reception every DTIM=1 (~102ms)		319		
	System with 1.8V WLAN beacon reception every DTIM=1 (~102ms)		490		

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6.12 Current Consumption - BLE Static Modes

PARAMETER	TEST CONDITION	SUPPLY	TYP	MAX	UNIT
TX, Max Duty Cycle	TX power = 0 dBm	V_{Main}	102		mA
		V_{PA}	35		
	TX power = 10 dBm	V_{Main}	102		
		V_{PA}	100		
	TX power = 20 dBm	V_{Main}	105		
		V_{PA}	250		
RX		V_{Main}	62		
		V_{PA}	0		

6.13 Current Consumption - Device States

Nominal device at room temp

MODE	DESCRIPTION	SUPPLY	TYP	UNIT
Shutdown	External supplies are available, device held in reset (nReset is low)	V_{Main} + V_{PP}	10	uA
		V_{PA}	2	
Sleep	Low power mode - RAM in retention	V_{Main} + V_{PP}	330	
		V_{PA}	2	

6.14 Timing and Switching Characteristics

6.14.1 Power Supply Sequencing

For proper operation of the CC330x device, perform the recommended power-up sequencing as follows:

1. All supplies (VDD_MAIN_IN, VDDA, VIO, VPA) must be available before nReset is released.
2. For an external slow clock, ensure that the clock is stable before nReset is deasserted (high).
3. The nReset pin should be held low for at least 10 us after stabilization of the external power supplies.

6.14.2 Clocking Specifications

The CC330x device uses two clocks for operation:

- A fast clock running at 40 MHz for WLAN/BLE functions
- A slow clock running at 32.768 kHz for low power modes

The slow clock can be generated internally or externally. The fast clock must be generated externally.

6.14.2.1 Slow Clock Generated Internally

In order to minimize external components, the slow clock can be generated by an internal oscillator. However, this clock is less accurate and consumes more power than sourcing the slow clock externally. For this scenario the Slow_CLK_IN pin should be left not connected.

6.14.2.2 Slow Clock Using an External Oscillator

For optimal power consumption, the slow clock can be generated externally by an oscillator or sourced from elsewhere in the system. The external source must meet the requirements listed below. This clock should be fed into the CC330x pin Slow_CLK_IN and should be stable before nReset is deasserted and device is enabled.

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6.14.2.2.1 External Slow Clock Requirements

PARAMETER		Description	MIN	TYP	MAX	UNIT
	Input slow clock frequency	Square wave		32768		Hz
	Frequency accuracy	Inital + temperature + aging			±250	ppm
	Input Duty cycle		30	50	70	%
T_r/T_f	Rise and fall time	10% to 90% (rise) and 90% to 10% (fall) of digital signal level			100	ns
V_{IL}	Input low level		0		0.35 x V_{IO}	V
V_{IH}	Input high level		0.65 x V_{IO}		1.95	V
	Input impedence		1			MΩ
	Input capacitance				5	pF

6.14.2.3 Fast Clock Using an External Crystal (XTAL)

The CC330x device supports a crystal-based fast clock (XTAL). The crystal is fed directly between HFXT_P and HFXT_M pins with suitable loading capacitors, and must meet the requirements below.

6.14.2.3.1 External Fast Clock XTAL Specifications

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Supported frequencies			40		MHz
Frequency accuracy	Initial + temperature + aging			+/- 25	ppm
Load Capacitance, C_L (1)		5		13	pF
Equivalent series resistance, ESR				30	Ω
Drive level			100		uW

(1) Load capacitance, C_L= [C1*C2] / [C1 + C2] + C_P, where C1, C2 are the capacitors connected on HFXT_P and HFXT_M, respectively, and C_P is the parasitic capacitance (typically 1 to 2 pF). For example, for C1 = C2 = 6.2pF and C_P = 2pF, then C_L = 5pF.

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6.15 Interface Timing Characteristics

6.15.1 SDIO Timing Specifications

SDIO is the main host interface for WLAN, and it supports a maximum clock rate of 52 MHz. The CC330x device also supports shared SDIO interface for both BLE and WLAN.

6.15.1.1 SDIO Timing Diagram - Default Speed

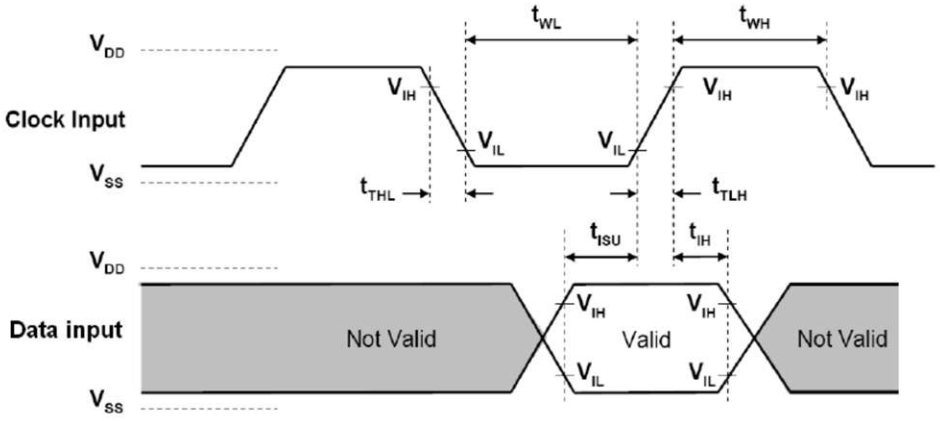

图 6-1. SDIO Default Input Timing

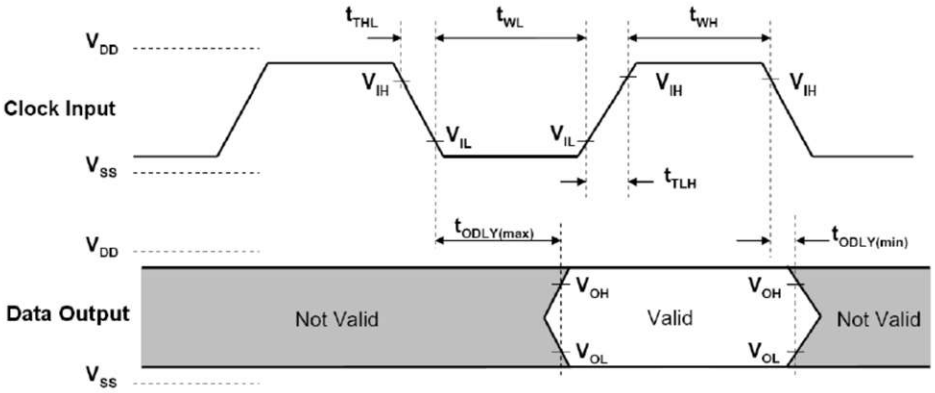

图 6-2. SDIO Default Output Timing

6.15.1.2 SDIO Timing Parameters - Default Speed

PARAMETER	DESCRIPTION	MIN	MAX	UNIT
f_{clock}	Clock frequency, CLK		26	MHz
t_{High}	High Period	10		ns
t_{Low}	Low Period	10		
t_{TLH}	Rise time, CLK		10	
t_{THL}	Fall time, CLK		10	
t_{ISU}	Setup time, input valid before CLK ↑	5		
t_{IH}	Hold time, input valid after CLK ↑	5		
t_{ODLY}	Delay time, CLK ↓ to output valid	2	14	
C_L	Capacitive load on outputs	15	40	pF

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6.15.1.3 SDIO Timing Diagram - High Speed

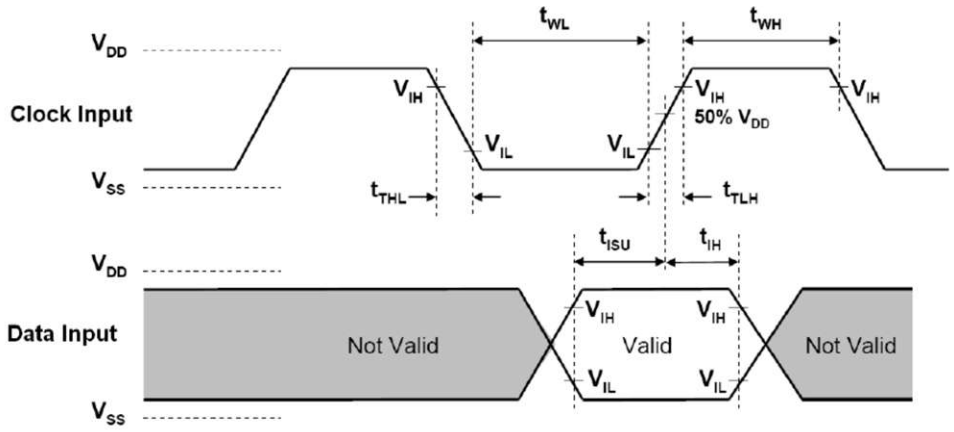

图 6-3. SDIO HS Input Timing

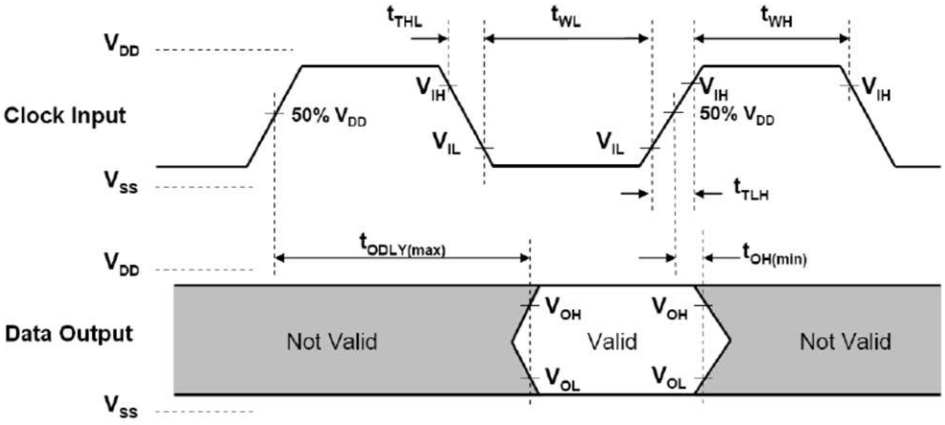

图 6-4. SDIO HS Output Timing

6.15.1.4 SDIO Timing Parameters - High Speed

PARAMETER	DESCRIPTION	MIN	MAX	UNIT
f_{clock}	Clock frequency, CLK		52	MHz
t_{High}	High Period	7		ns
t_{Low}	Low Period	7		
t_{TLH}	Rise time, CLK		3	
t_{THL}	Fall time, CLK		3	
t_{ISU}	Setup time, input valid before CLK ↑	6		
t_{IH}	Hold time, input valid after CLK ↑	2		
t_{ODLY}	Delay time, CLK ↓ to output valid	2	14	
C_L	Capacitive load on outputs	15	40	pF

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6.15.2 SPI Timing Specifications

SPI is another host interface for WLAN. The CC330x device also supports shared SPI interface for both BLE and WLAN.

6.15.2.1 SPI Timing Diagram

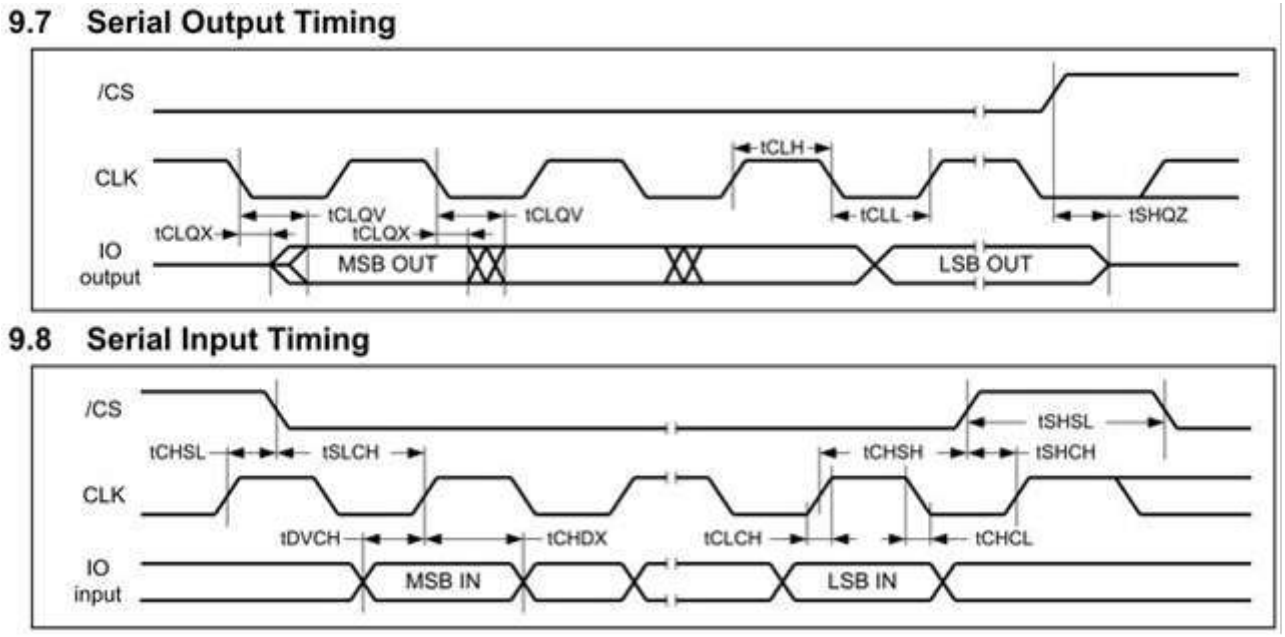

图 6-5. SPI Timing

6.15.2.2 SPI Timing Parameters

PARAMETER	DESCRIPTION	MIN	MAX	UNIT
f_{clock}	Clock frequency, CLK		26	MHz
t_{High}	High Period	10		ns
t_{Low}	Low Period	10		
t_{TLH}	Rise time, CLK		3	
t_{THL}	Fall time, CLK		3	
t_{CSsu}	CS Setup time, CS valid before CLK ↑	3		
t_{ISU}	PICO, input valid before CLK ↑	3		
t_{IH}	PICO Hold time, input valid after CLK ↑	3		
t_{Dr}, t_{Df} - Active	Delay time, CLK ↑ / ↓ to output valid	2	10	
t_{Dr}, t_{Df} - Sleep	Delay time, CLK ↑ / ↓ to output valid		12	
C_L	Capacitive load on outputs	15	40	pF

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6.15.3 UART 4-Wire Interface

UART is the main host interface for BLE, which supports host controller interface (HCI) transport layer.

6.15.3.1 UART Timing Parameters

PARAMETER	CONDITION	MIN	TYP	MAX	UNIT
Baud rate		37.5		4364	kbps
Baud rate accuracy per byte	Receive/Transmit	-2.5		+1.5	%
Baud rate accuracy per bit	Receive/Transmit	-12.5		+12.5	%
CTS low to TX_DATA on		0	2		ms
CTS high to TX_DATA off	Hardware flow control			1	Byte
CTS high pulse width		1			bit
RTS low to RX_DATA on		0	2		ms
RTS high to RX_DATA off	Interupt set to 1/4 FIFO			16	Byte

7 Applications, Implementation, and Layout

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’ s customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

图 7-1 shows the reference schematic for the CC3301 using an optimized bill of materials.

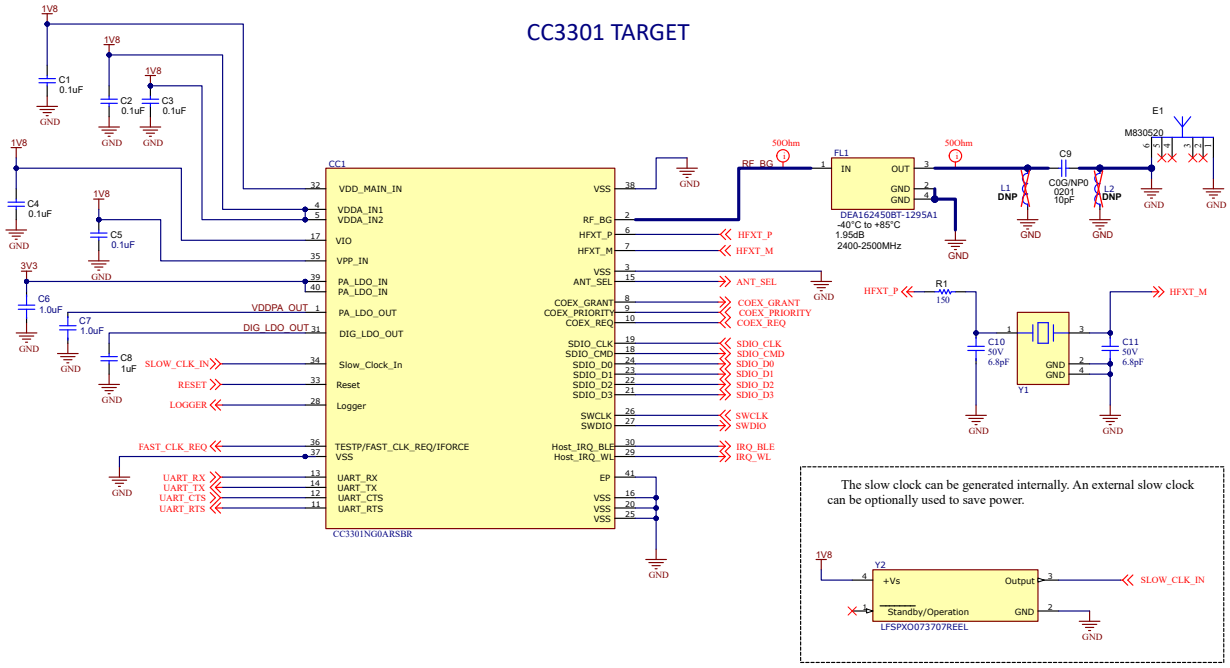

图 7-1. CC3301 Reference Schematic

1. The slow clock can be generated internally. An external slow clock can be optionally used to save power.
2. For more information on antenna selection and matching, please see the CC33xx Hardware Integration.

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8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 第三方产品免责声明

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8.2 器件命名规则样板文件

器件开发演变流程：

X 试验器件不一定代表最终器件的电气规范标准，并且可能不使用生产组装流程。

P 原型器件不一定是最终器件模型，并且不一定符合最终电气标准规范。

无 完全合格的芯片模型的生产版本。

支持工具开发演变流程：

TMDX 还未经德州仪器 (TI) 完整内部质量测试的开发支持产品。

TMDS 完全合格的开发支持产品。

X 和 P 器件和 TMDX 开发支持工具在供货时附带如下免责条款：

器件开发演变流程：

TMX 试验器件不一定代表最终器件的电气规范标准，并且可能不使用生产组装流程。

TMP 原型器件不一定是最终器件模型，并且不一定符合最终电气标准规范。

TMS 完全合格的芯片模型的生产版本。

支持工具开发演变流程：

TMDX 还未经德州仪器 (TI) 完整内部质量测试的开发支持产品。

TMDS 完全合格的开发支持产品。

TMX 和 TMP 器件和 TMDX 开发支持工具供货时附带如下免责条款：

“开发的产品用于内部评估用途。”

生产器件和 TMDS 开发支持工具已进行完全特性描述，并且器件的质量和可靠性已经完全论证。TI 的标准保修证书适用。

预测显示原型器件（X 或者 P）的故障率大于标准生产器件。由于这些器件的预期最终使用故障率仍未确定，故德州仪器 (TI) 建议请勿将这些器件用于任何生产系统。请仅使用合格的生产器件。

8.3 Tools and Software

Design Kits and Evaluation Modules

CC330x Reference Design Files	CC330x reference design CAD source files. TI recommends using this design as a reference when creating the layout in order to achieve the RF performance listed in this datasheet.
CC3301 BoosterPack plug-in module	The CC3301 BoosterPack™ plug-in module (BP-CC3301) is a test and development board that can be easily connected to TI LaunchPad™ development kits or processor boards; thus enabling rapid software development.

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CC3301 M.2 card plug-in module	The CC3301 M.2 card plug-in module (M2-CC3301) is a test and development board that can be easily connected to TI processor boards or other processor boards with an M.2 Key E interface support; thus enabling rapid software development.

Software

SimpleLink Wi-Fi Toolbox	SimpleLink Wi-Fi Toolbox is a collection of tools to help development and testing of the CC33xx. The Wi-Fi toolbox package provides all the capabilities required to debug and monitor WLAN/Bluetooth® Low Energy firmware with a host, perform RF validation tests, run pretest for regulatory certification testing, and debug hardware and software platform integration issues.
CC33xx device drivers	The CC33XX are single-chip Wi-Fi 6 and Bluetooth Low Energy 5.4 companion devices suitable for both Linux and RTOS based systems. CC33XX-SOFTWARE is a collection of software development sources aimed to facilitate quick setup, out-of-box experience, and accelerate development in Linux or RTOS environments.

8.4 Documentation Support

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击*通知* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

Application Reports

CC33xx Production Line Guide	Texas Instruments™ provides many resources in order to assist users in quickly examining the functionality and performance of their devices. This document provides the necessary information to guide the user in production line testing for CC33xx. The device's functions can be checked using tools and software provided by Texas Instruments. Performance testing is more involved as external equipment is required for thorough examination.
SimpleLink CC33xx Security Features	This document describes the CC33xx security related features, which are made available to vendors through an ecosystem that incorporates simple and concise APIs, tools, and documentation

User's Guides

CC33xx WLAN Features User's Guide	This document provides information about CC33xx family of devices and Wi-Fi® features, as well as TI proprietary enhancements. The document does not provide the complete application programming interface (API) set, but a high-level overview of the features.
CC33xx Hardware Integration	This document describes how to integrate the CC330x into any system and the hardware requirements for this device. Layout and schematic considerations are listed here as well, which TI highly recommends following in order to achieve the device performance listed in this datasheet.

8.5 支持资源

TI E2E™ 中文支持论坛是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的使用条款。

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8.7 静电放电警告

静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.8 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from October 5, 2023 to December 19, 2023 (from Revision C (October 2023) to Revision D (December 2023))	Page
• Updated specifications data and test conditions to production values	8
• Updated reference schematic	18

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10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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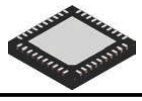
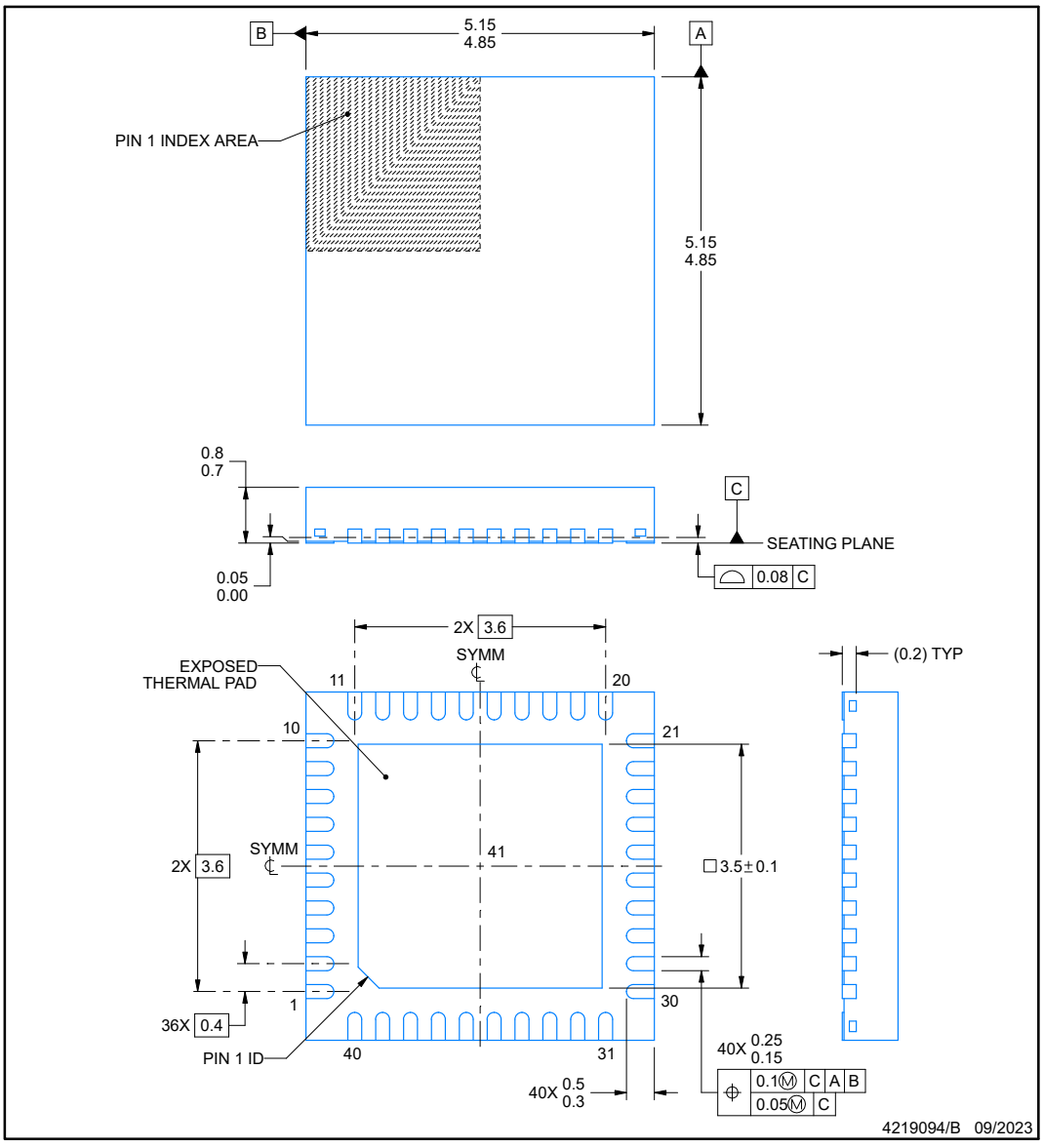
RSB0040B



PACKAGE OUTLINE

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

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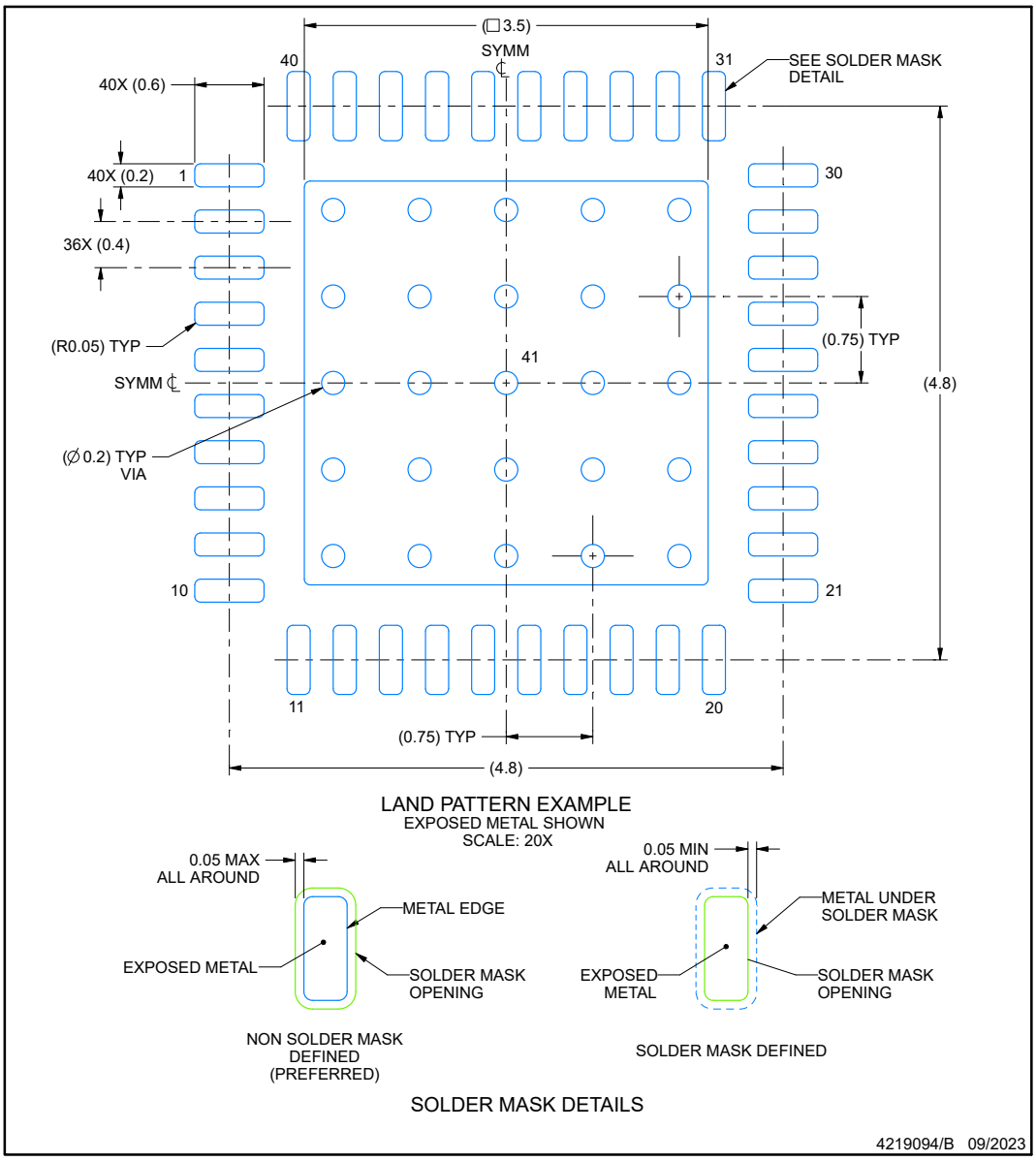
EXAMPLE BOARD LAYOUT

RSB0040B

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

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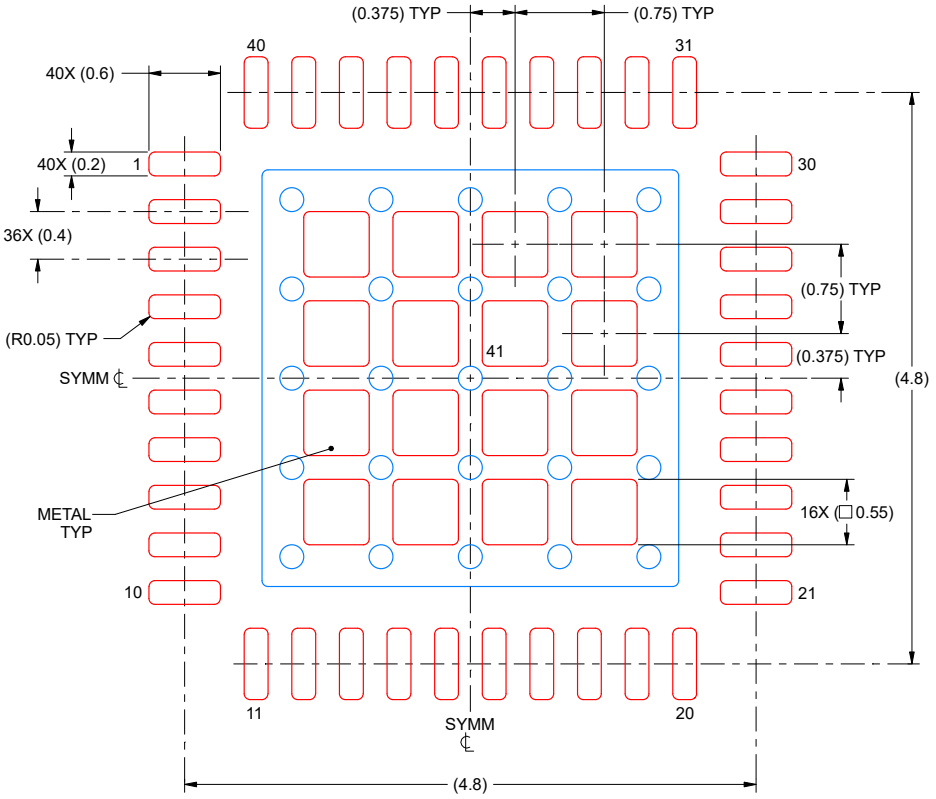
EXAMPLE STENCIL DESIGN

RSB0040B — **WQFN - 0.8 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 41
40% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4219094/B 09/2023

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CC3300ENJARSBR	ACTIVE	WQFN	RSB	40	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	CC3300 ENJA	Samples
CC3301ENJARSBR	ACTIVE	WQFN	RSB	40	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	CC3301 ENJA	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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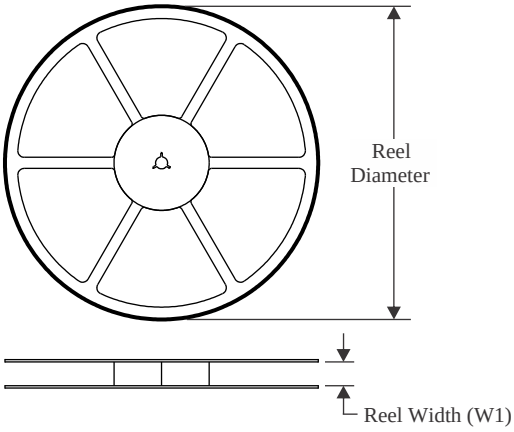
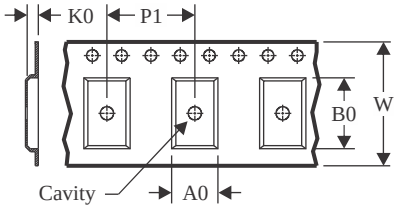
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

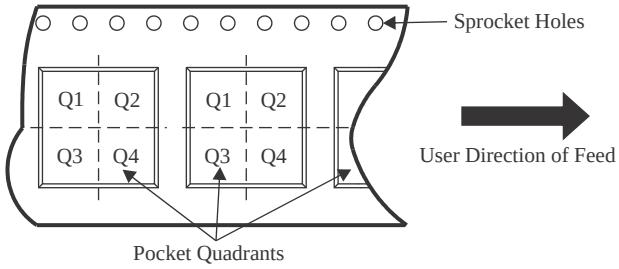


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

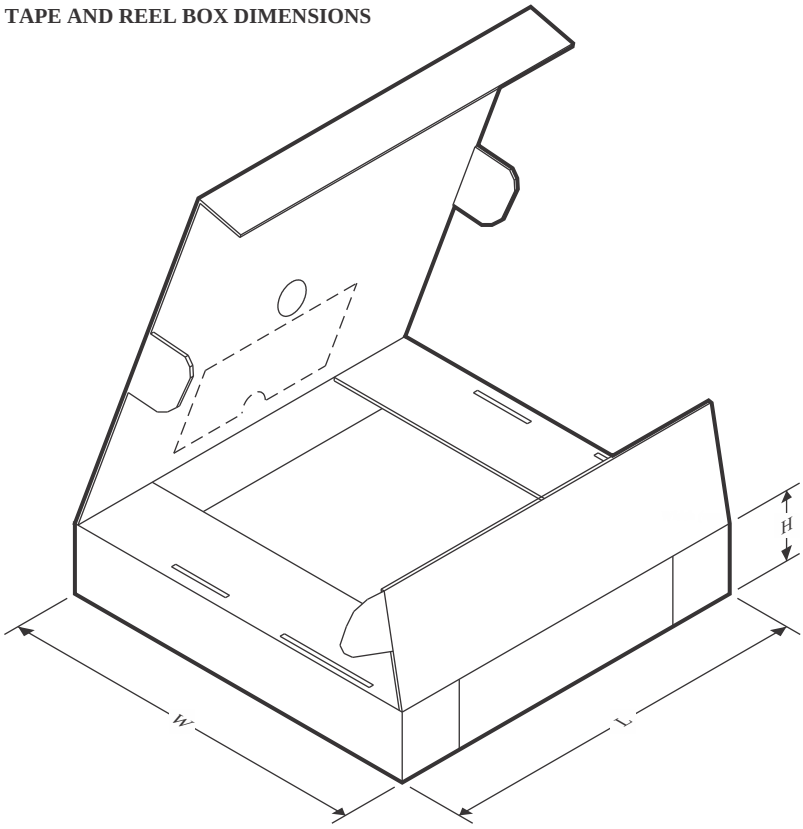
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CC3300ENJARSBR	WQFN	RSB	40	3000	330.0	12.4	5.3	5.3	1.1	8.0	12.0	Q2
CC3301ENJARSBR	WQFN	RSB	40	3000	330.0	12.4	5.3	5.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CC3300ENJARSBR	WQFN	RSB	40	3000	367.0	367.0	35.0
CC3301ENJARSBR	WQFN	RSB	40	3000	367.0	367.0	35.0

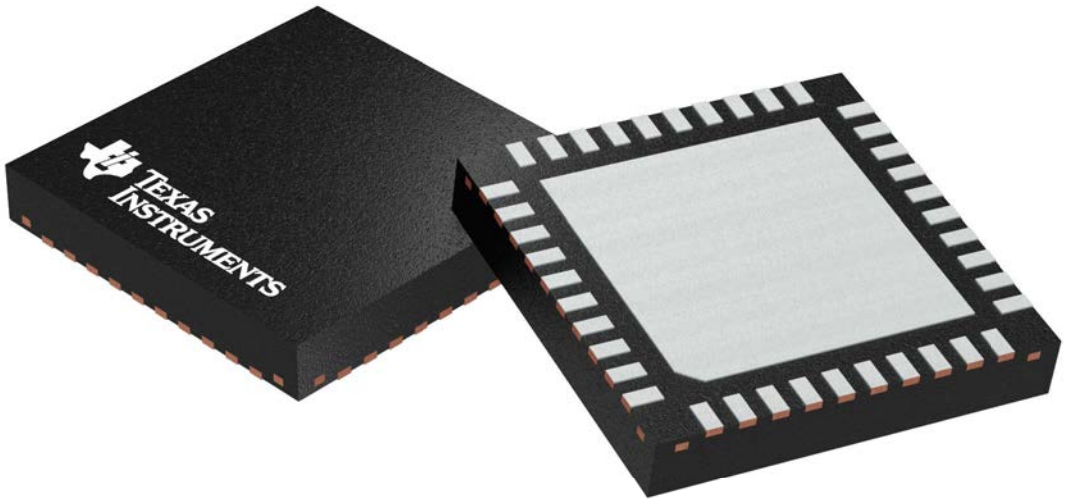
GENERIC PACKAGE VIEW

RSB 40

WQFN - 0.8 mm max height

5 x 5 mm, 0.4 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



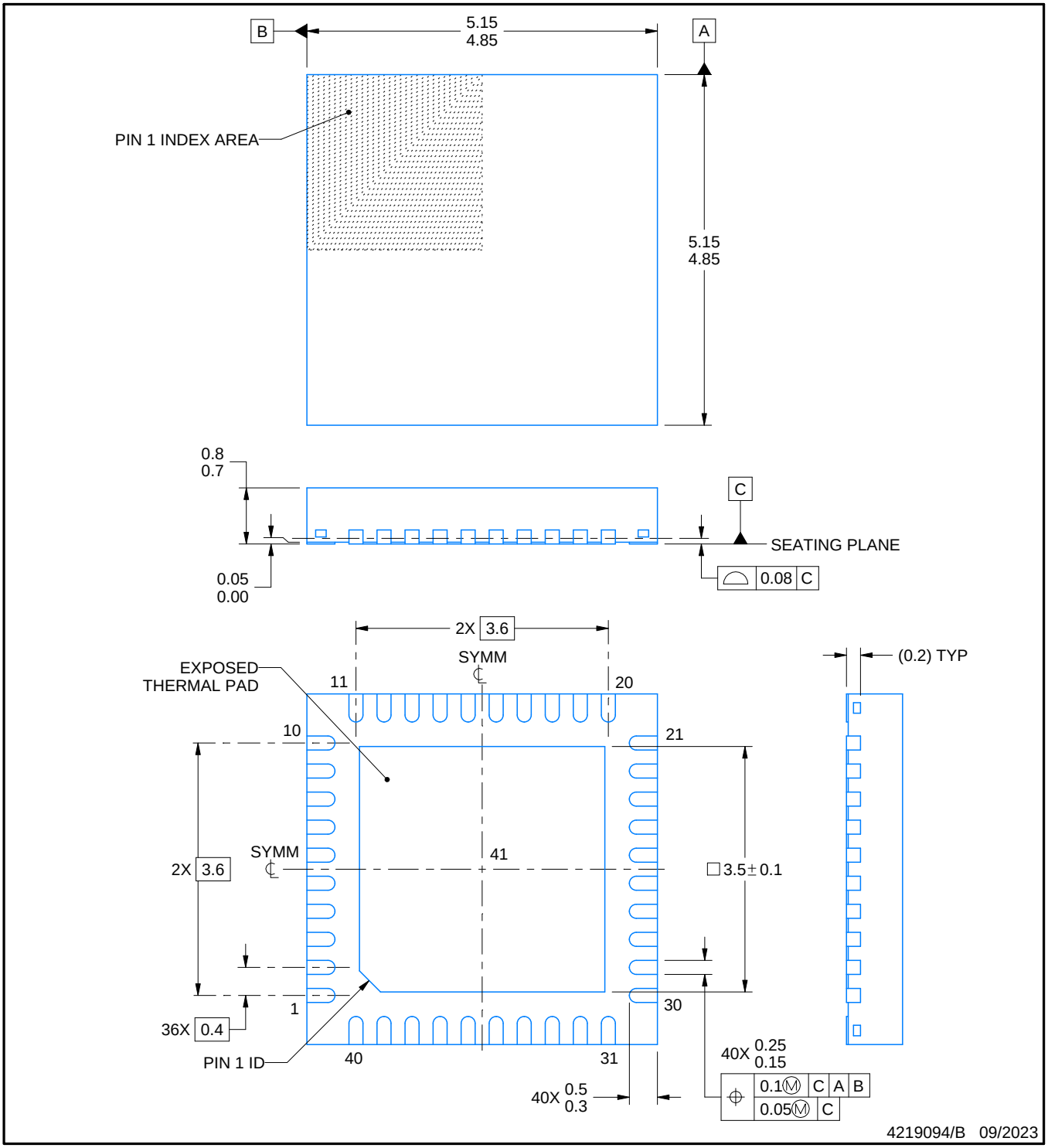
Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

RSB0040B

PACKAGE OUTLINE

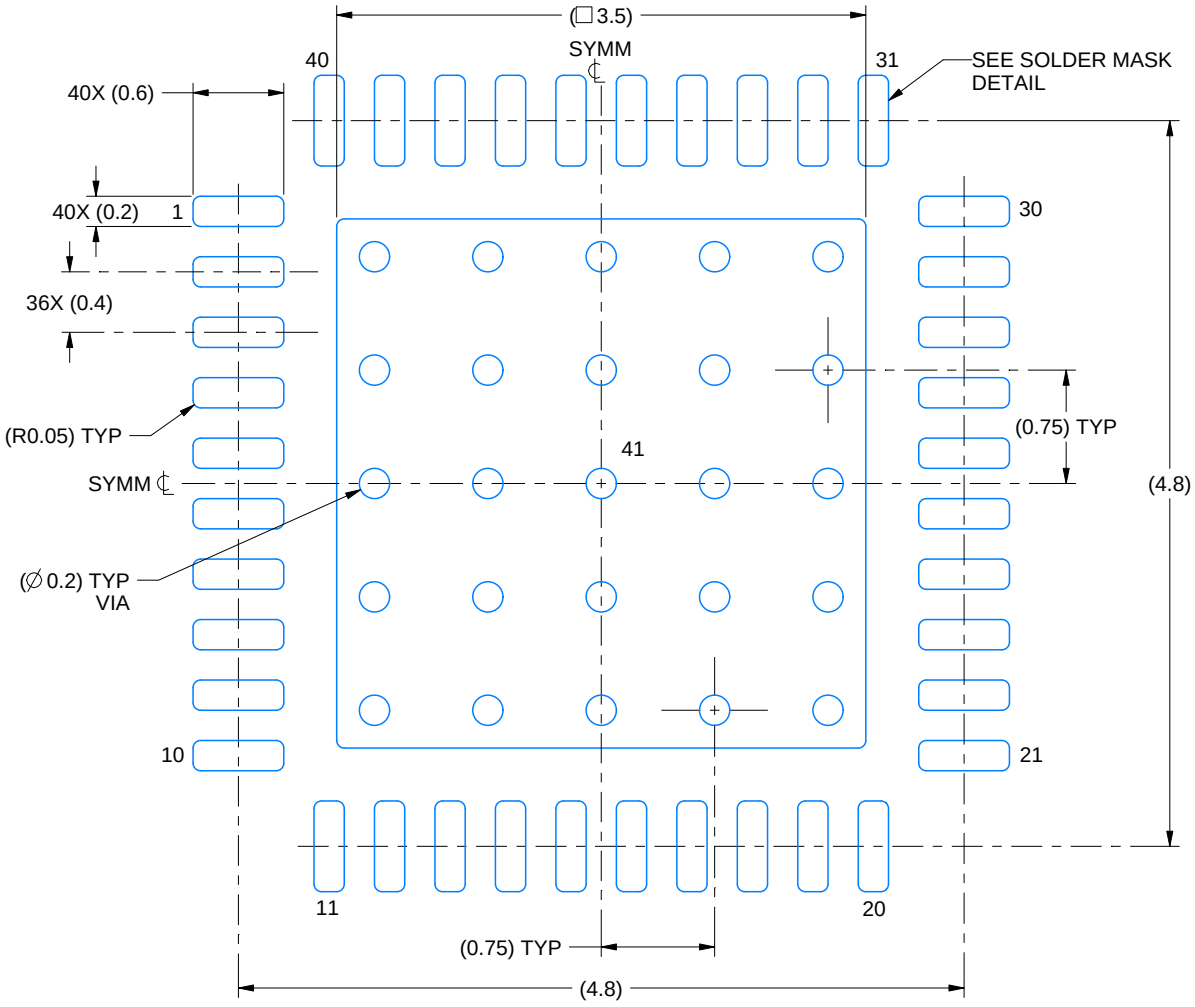
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

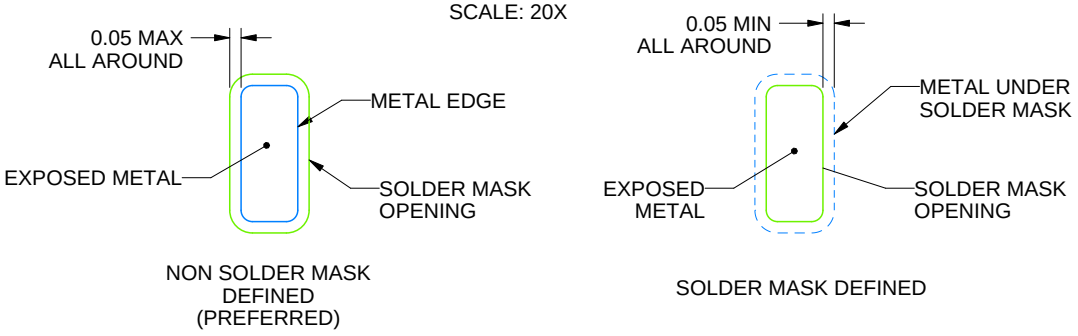


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X

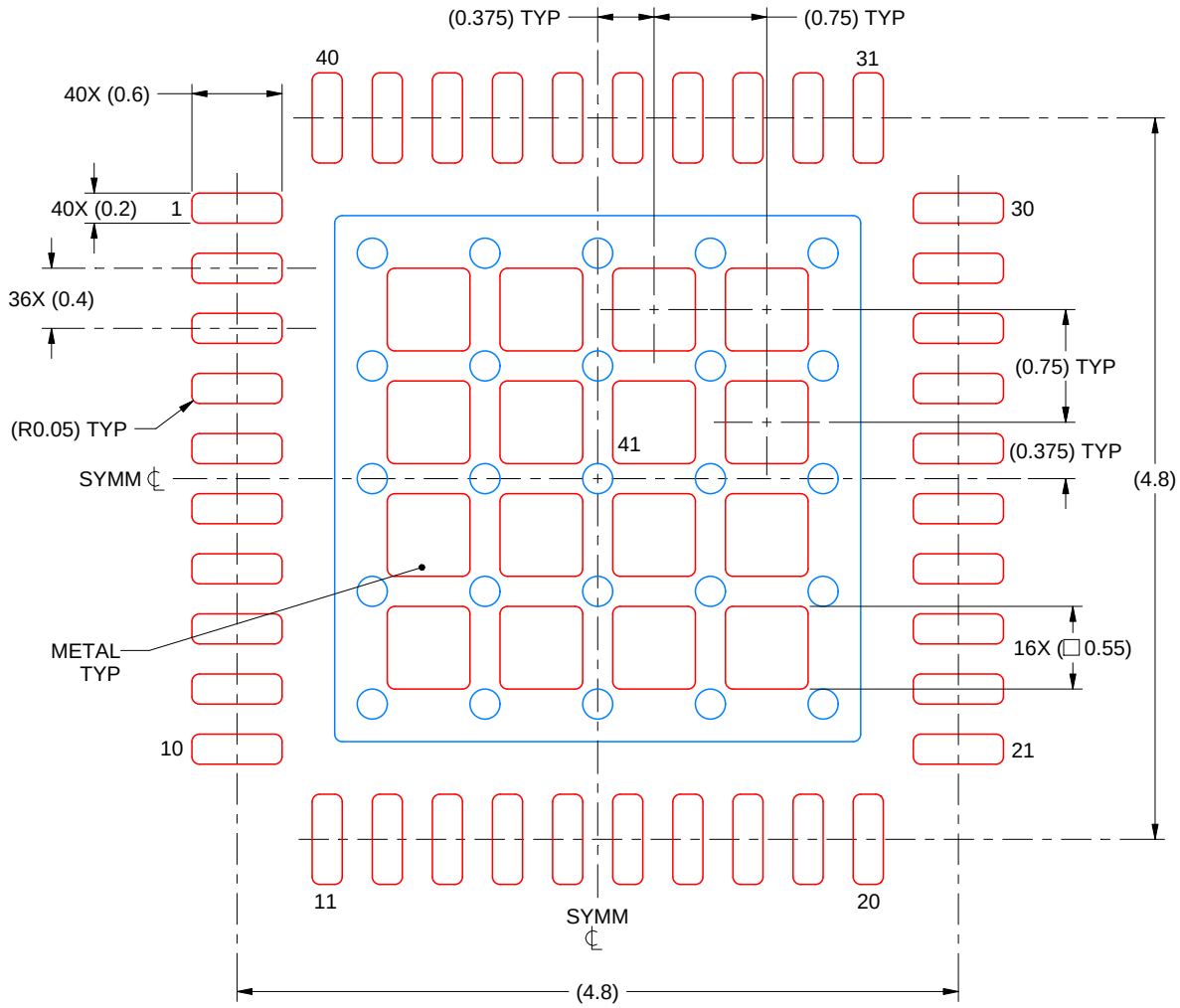


SOLDER MASK DETAILS

4219094/B 09/2023

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 41
40% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4219094/B 09/2023

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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